Part Number	Jumber Customer				
Category	Parameter		Specification	Measurement Method	
OverallWafer	1.0	Diameter	150.00 +/- 0.50 mm		
	2.0	Primary Flat Orientation	{110}+/-0.5 degree	Wafer Vendor	
	3.0	Primary Flat Length	57.50 +/- 2.50 mm	Wafer Vendor	
	4.0	Secondary Flat Orientation	none		
	5.0	Overall Thickness	627.00 +/- 11.00 μm	ADE, 100%	
	6.0	Total Thickness Variation (TTV)	<5.00µm	Guaranteed by Process	
	7.0	Global Flatness (TIR)	<3.00um	ADE 100%	
	8.0	Bow	<75.00µm	ADE to ASTM F534, 20%	
	9.0	Warp	<75.00µm	ADE to ASTM F657, 20%	
	10.0	Edge Chips	0	Bright Light, 100% (note 2)	
	11.0	Edge Exclusion	7mm		
HandleSilicon	12.0	Handle Growth Method	CZ or FZ	Wafer Vendor	
	13.0	Handle Orientation	{100} +/- 1 degree	Wafer Vendor	
	14.0	Handle Thickness	600.00 +/- 10.00 μm	ADE, 100% - pre oxidation	
	15.0	Handle Doping Type	N	Wafer Vendor	
	16.0	Handle Dopant	Phosphorous	Wafer Vendor	
	17.0	Handle Resistivity	1 - 10 Ohmem	Wafer Vendor	
	18.0	Backside Finish	Polished Prior to oxidation. Thermal oxide remains on back. Some scraches accepatable with laser marking	Wafer Vendor	
BuriedOxide	19.0	Oxide Type	Thermal		
	20.0	Oxide Thickness	20,000.00 +/- 1,000.00 A	Nanospec centre point, 4%	
	21.0	Oxide formed on	Handle Wafer		
DeviceSilicon	22.0	Device Growth Method	CZ	Wafer Vendor	
	23.0	Oxygen Concentration	< 8E17 cm-3	Wafer Vendor	
	24.0	Carbon Concentration	< 2E16 cm-3	Wafer Vendor	
	25.0	Device Orientation	{100} +/- 0.5 degree	Wafer Vendor	
	26.0	Nominal Thickness	25.00 +/- 1.00 μm	FTIR, 100% 9-Pt (note 3)	
	27.0	Distance to device silicon edge from wafer edge	<= 1.5mm	Typical by Process	
	28.0	Device Doping Type	Ν	Wafer Vendor	
	29.0	Device Dopant	Phosphorous	Wafer Vendor	
	30.0		1- 10 Ohmcm	Wafer Vendor	
	31.0	-	none	implant vendor	
	32.0		0	Bright Light, 100% (note 2)	
	33.0		<25mm total length	Bright Light, 100% (note 2)	
	34.0		none	Bright Light, 100% (note 2)	

Icemos Technology Ltd

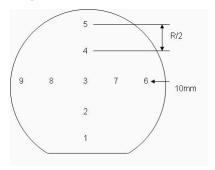
**Product Specification** 

1000.294302

Part Number		Customer		
Category	Parameter	Specification	Measurement Method	
Shipping Details	Wafer per box :	Max 25		
	Packaging :	Taped Polypropylene Wafer Box Empak, Ultrapak, 150.00mm Antistatic Double Bagging		
	Lot Shipment Data	Device Thickness Bow / Warp Data Handle and SOI Thickness		
Explanatory Notes	1. Microscope inspection performed using microscope scan as below. 5x objective.			

2. All bright light inspections performed exclude all wafer area outside the edge exclusion defined in Overall Wafer, Edge Exclusion. High intensity bright lamp inspection as per ASTM F523.

3. 9 point measurement are as shown in the diagram below:



Additional Information